

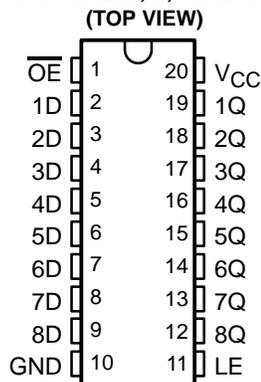
SN54BCT573, SN74BCT573 OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

SCBS071B – AUGUST 1990 – REVISED MARCH 2003

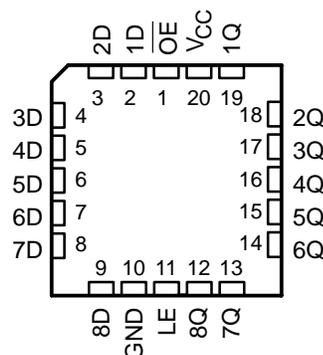
- Operating Voltage Range of 4.5 V to 5.5 V
- State-of-the-Art BiCMOS Design Significantly Reduces I_{CCZ}
- Full Parallel Access for Loading

- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

SN54BCT573 . . . J OR W PACKAGE
SN74BCT573 . . . DW, N, OR NS PACKAGE



SN54BCT573 . . . FK PACKAGE
(TOP VIEW)



description/ordering information

These 8-bit latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight latches of the 'BCT573 devices are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When the latch enable is taken low, the Q outputs are latched at the logic levels that were set up at the D inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

\overline{OE} does not affect internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tube	SN74BCT573N	SN74BCT573N
	SOIC – DW	Tube	SN74BCT573DW	BCT573
		Tape and reel	SN74BCT573DWR	
	SOP – NS	Tape and reel	SN74BCT573NSR	BCT573
–55°C to 125°C	CDIP – J	Tube	SNJ54BCT573J	SNJ54BCT573J
	CFP – W	Tube	SNJ54BCT573W	SNJ54BCT573W
	LCCC – FK	Tube	SNJ54BCT573FK	SNJ54BCT573FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

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recommended operating conditions (see Note 3)

		SN54BCT573			SN74BCT573			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{IK}	Input clamp current			-18			-18	mA
I_{OH}	High-level output current			-12			-15	mA
I_{OL}	Low-level output current			48			64	mA
T_A	Operating free-air temperature	-55		125	0		70	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54BCT573		SN74BCT573		UNIT	
			MIN	TYP†	MAX	MIN		TYP†
V_{IK}	$V_{CC} = 4.5\text{ V}$,	$I_I = -18\text{ mA}$			-1.2		-1.2	V
V_{OH}	$V_{CC} = 4.5\text{ V}$	$I_{OH} = -3\text{ mA}$	2.4	3.3	2.4	3.3	V	
		$I_{OH} = -12\text{ mA}$	2	3.2				
		$I_{OH} = -15\text{ mA}$			2	3.1		
V_{OL}	$V_{CC} = 4.5\text{ V}$	$I_{OL} = 48\text{ mA}$		0.38	0.55		V	
		$I_{OL} = 64\text{ mA}$				0.42		0.55
I_I	$V_{CC} = 5.5\text{ V}$,	$V_I = 5.5\text{ V}$			0.4		0.4	mA
I_{IH}	$V_{CC} = 5.5\text{ V}$,	$V_I = 2.7\text{ V}$			20		20	μA
I_{IL}	$V_{CC} = 5.5\text{ V}$,	$V_I = 0.5\text{ V}$			-0.6		-0.6	mA
$I_{OS}‡$	$V_{CC} = 5.5\text{ V}$,	$V_O = 0$	-100		-225	-100	-225	mA
I_{OZH}	$V_{CC} = 5.5\text{ V}$,	$V_O = 2.7\text{ V}$			50		50	μA
I_{OZL}	$V_{CC} = 5.5\text{ V}$,	$V_O = 0.5\text{ V}$			-50		-50	μA
I_{CCL}	$V_{CC} = 5.5\text{ V}$,	Outputs open			62		62	mA
I_{CCH}	$V_{CC} = 5.5\text{ V}$,	Outputs open			8		8	mA
I_{CCZ}	$V_{CC} = 5.5\text{ V}$,	Outputs open			8		8	mA
C_i	$V_{CC} = 5\text{ V}$,	$V_I = 2.5\text{ V}$ or 0.5 V		5.5		5.5		pF
C_o	$V_{CC} = 5\text{ V}$,	$V_O = 2.5\text{ V}$ or 0.5 V		7.5		7.5		pF

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

		$V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$		SN54BCT573		SN74BCT573		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, LE high	4		4		4		ns
t_{su}	Setup time, data before LE↓	1		2.5		1		ns
t_h	Hold time, data after LE↓	4		4		4		ns



SN54BCT573, SN74BCT573
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WITH 3-STATE OUTPUTS

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

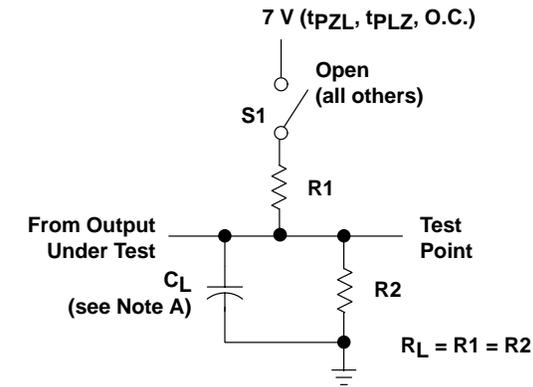
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5$ V, $T_A = 25^\circ$ C			SN54BCT573		SN74BCT573		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	Q	2	5	7.2	1	9.8	2	8.4	ns
t_{PHL}			2.8	5.9	8.2	1.5	10.3	2.8	9.6	
t_{PLH}	LE	Q	2.4	6.1	7.2	2	9.7	2.4	8.1	ns
t_{PHL}			2.9	5.2	7.1	2	8.8	2.9	7.8	
t_{PZH}	\overline{OE}	Q	3	6.2	8.5	2.5	11	3	10.4	ns
t_{PZL}			4.3	7.1	9.3	3.5	11.5	4.3	11	
t_{PHZ}	\overline{OE}	Q	2.2	3.9	5.6	1.5	7.2	2.2	6	ns
t_{PLZ}			1.7	3.6	5.2	1	7	1.7	6	



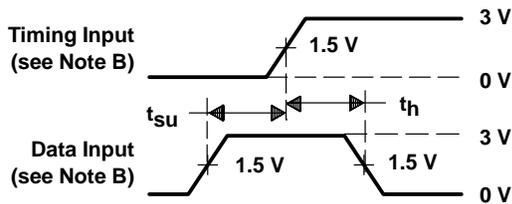
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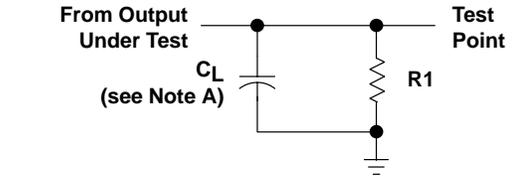
PARAMETER MEASUREMENT INFORMATION



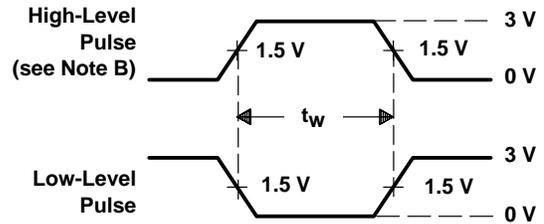
LOAD CIRCUIT FOR
3-STATE AND OPEN-COLLECTOR OUTPUTS



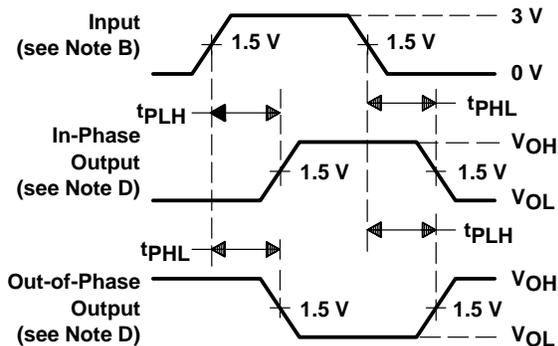
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



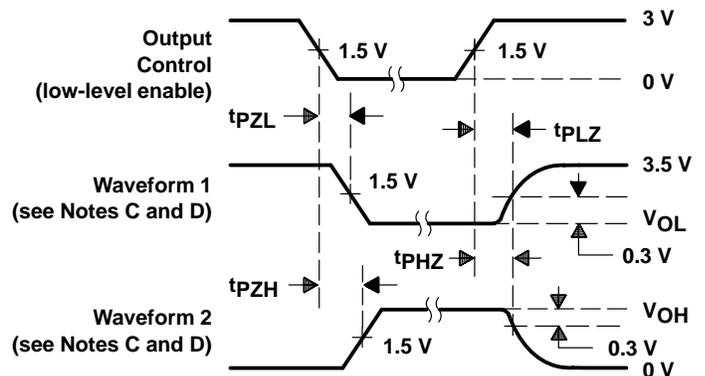
LOAD CIRCUIT FOR
TOTEM-POLE OUTPUTS



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES (see Note D)



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

- NOTES:
- C_L includes probe and jig capacitance.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $t_r = t_f \leq 2.5$ ns, duty cycle = 50%.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - The outputs are measured one at a time with one transition per measurement.
 - When measuring propagation delay times of 3-state outputs, switch S1 is open.
 - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9583501Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9583501QRA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
5962-9583501QSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type
SN74BCT573DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT573DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT573DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT573DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT573DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT573DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT573N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74BCT573NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74BCT573NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT573NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT573NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54BCT573FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54BCT573J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54BCT573W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

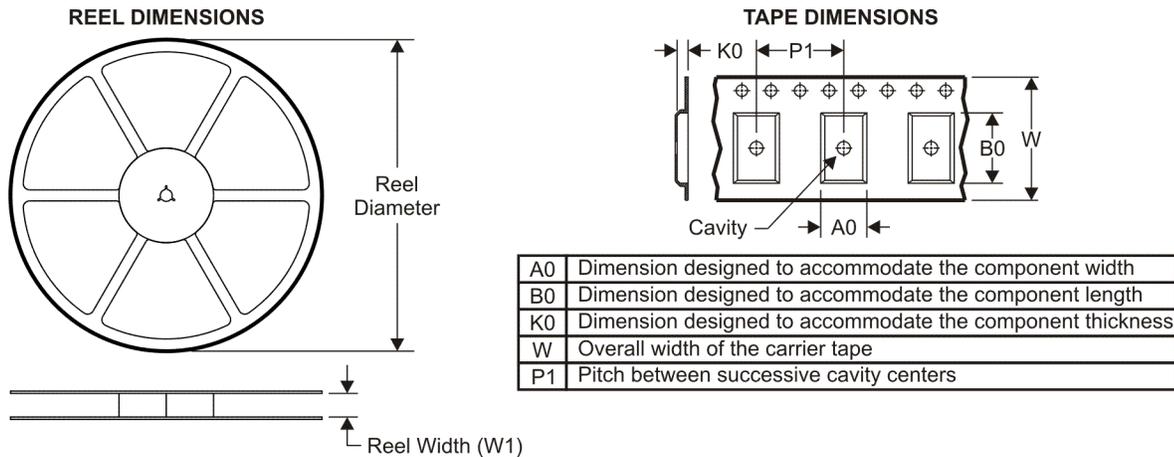
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

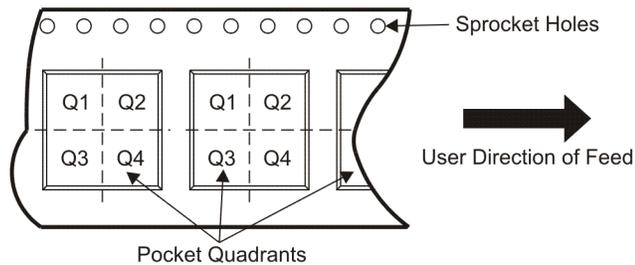
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TAPE AND REEL INFORMATION



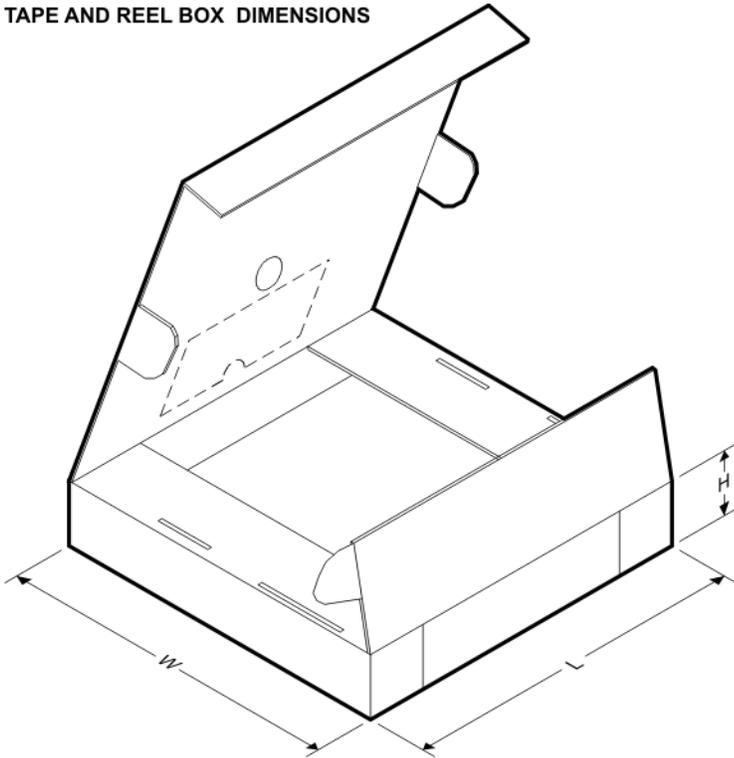
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74BCT573DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

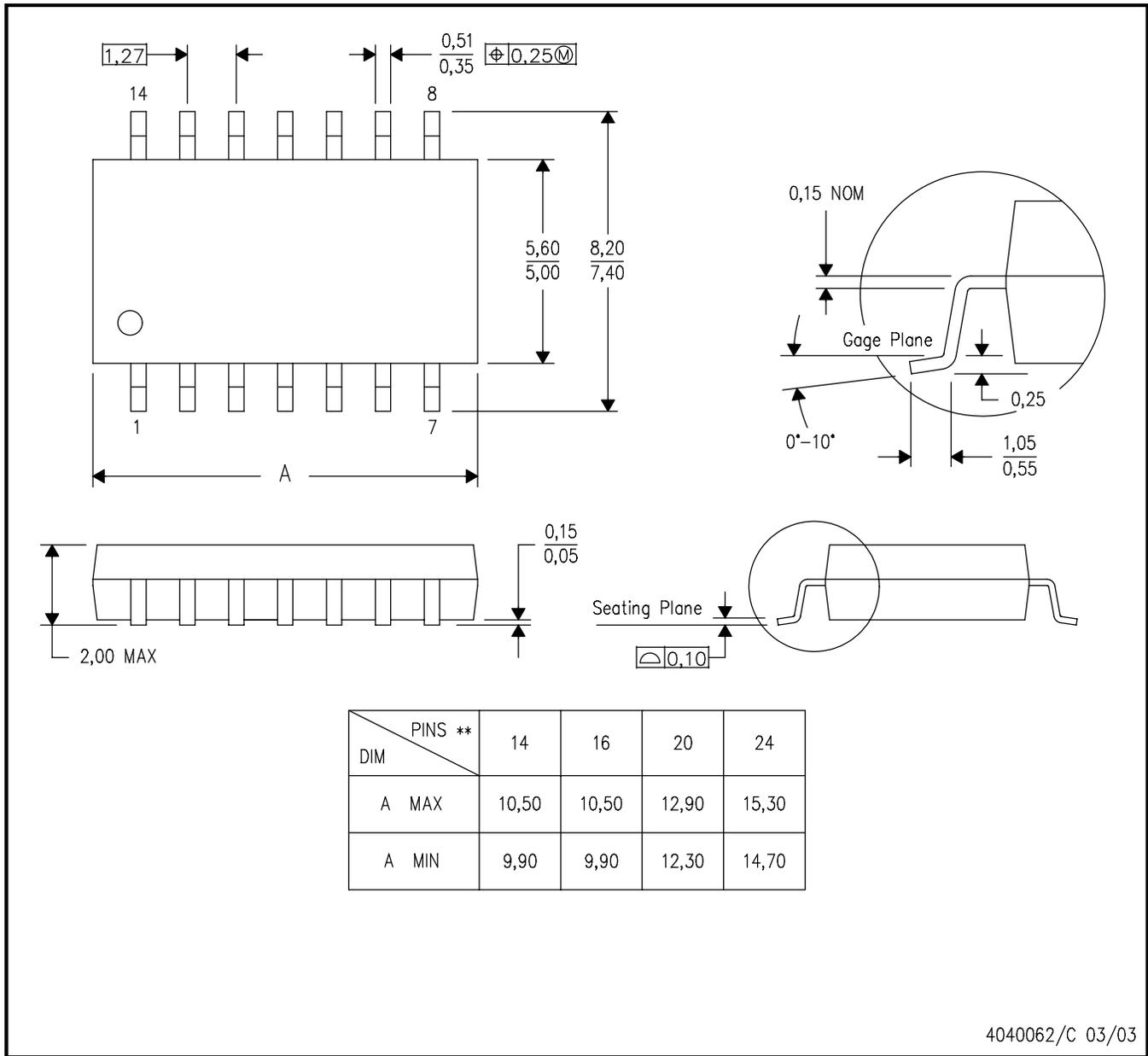
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74BCT573DWR	SOIC	DW	20	2000	346.0	346.0	41.0

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

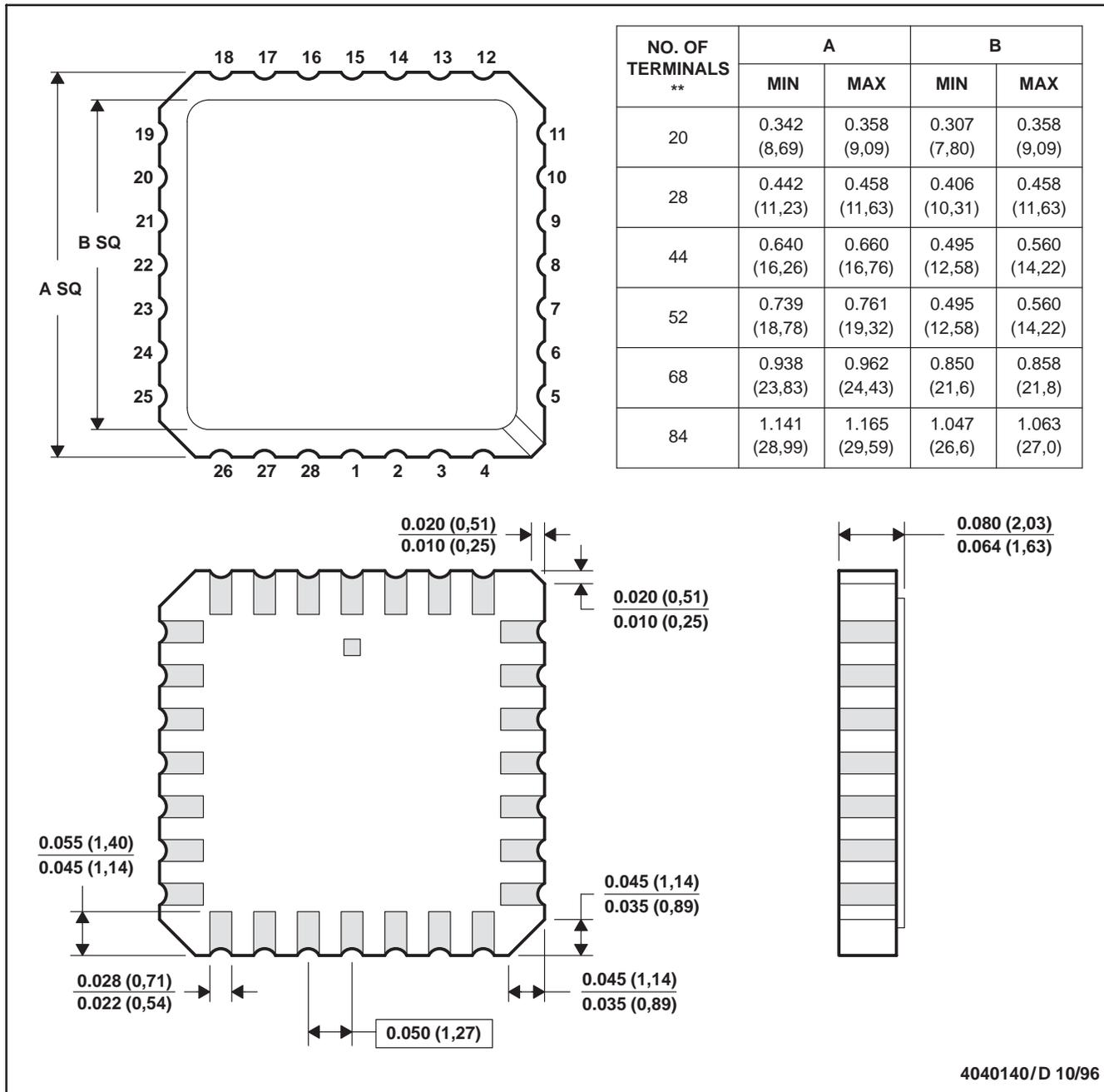


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

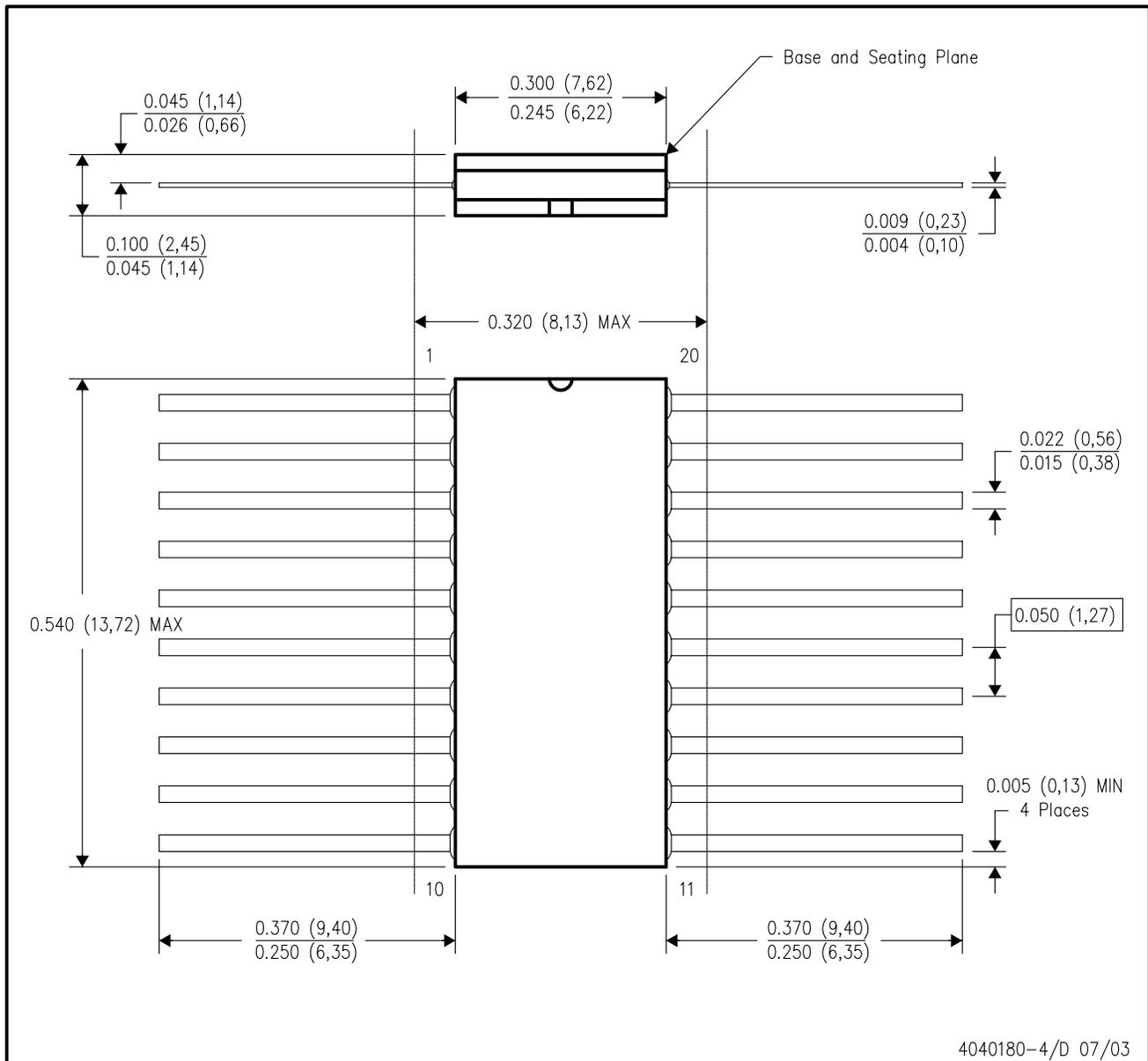


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

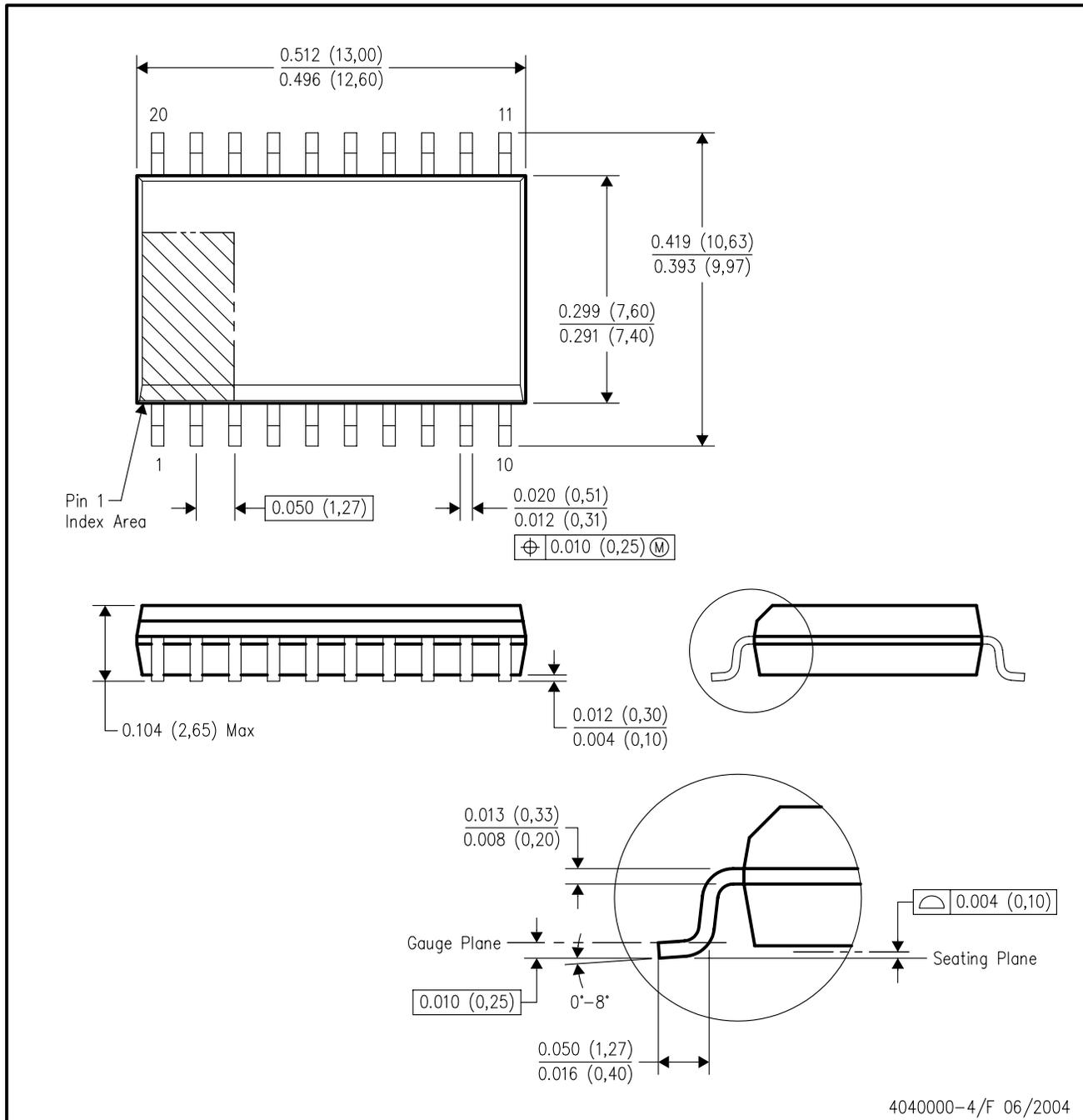
CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within Mil-Std 1835 GDFP2-F20

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AC.

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